

ABSTRACT

The invention comprises a method for joining pieces of unseasoned or dried wood, by finger jointing or other joining technique. The wood may have a moisture content above the fibre saturation point of the wood, and as high as 50% or 100% or higher moisture content. An adhesive having a sufficiently high molecular weight or viscosity to avoid adhesive degradation or migration from moisture in the wood during forming and curing of the joint, or which will cure to achieve such a sufficiently high molecular weight or viscosity during forming and curing of the joint is employed. Optionally a cure promotor or chemical which increases the rate of cure of the adhesive may be used. Preferred adhesives are formaldehyde based adhesives. Preferred cure promotor or chemicals are ammonia or amine compounds, organic acids including low molecular weight carboxylic acids, and Lewis or Bronsted class acids.

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